

Patent

Attorney Docket No. MTI-31607

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313 INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY. DOCKET NO.	Serial No.
	MTI-31607	10/050,507
	Applicant	Confirmation No.
	Teck Kheng Lee	7687
	Filing Date	Group Art Unit
	January 16, 2002	2813

FOREIGN PATENT OR PUBLISHED FOREIGN PATENT APPLICATION

Examiner Initial		Document Number	Publication Date	Country	Int'l Class	Sub-Class	Translation (Yes/No)
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CAT	A2	2001077294	03-23-01	JP	H01L	25/065	Yes
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